

## Ventiva Showcases Fan-less Cooling Solution in Intel-powered PC Concept

Ventiva ICE technology replaces mechanical fans with electronic airflow, showing off a proof-of-concept laptop design that's thin, silent, and totally cool.

FREMONT, Calif. – January 9, 2025 – Ventiva®, the leader in thermal solutions, today announced that its Ventiva ICE9® thermal management suite is being featured in a fan-less proof-of-concept laptop design, powered by Intel Lunar Lake processors at CES. By collaborating with Dell Technologies and Intel on the PC design, this concept introduces a new level of silent productivity for sub-12mm laptops.

"Ventiva ICE® technology offers a revolutionary approach to help achieve thin, light, and silent laptop designs that offer great performance," said Josh Newman, Vice President, Client Computing Group, and General Manager, Product Marketing & Management, Intel. "Intel is excited about the result of the close co-engineering collaboration with Ventiva and Dell Technologies to help ready their technology for future Intel Core Ultra devices."

"The performance and efficiency of Intel's Lunar Lake processors, along with Dell's system design expertise and Ventiva's thin, silent air movers, resulted in a truly groundbreaking machine," said Carl Schlachte, Chairman, President, and CEO of Ventiva. "The overwhelming reaction to this 'no-compromises' fan-less laptop has motivated the entire Ventiva team to continue pushing the boundaries of what ICE technology can achieve. We look forward to creating even more incredibly cool machines with Intel."

Ventiva's ICE9 thermal management suite is based on the company's patented <u>lonic Cooling</u>

Engine (ICE®) technology, which eliminates the need for mechanical fans, using intelligent software control to enable optimal performance in electronics devices—without any moving parts, noise, or vibration. The ultra-compact ICE9 solution enables laptop designs with a height of less than 12 mm, rivaling the thinnest laptops on the market today. Its space-efficient form factor not only supports sleek, thin designs but also provides original equipment manufacturers (OEMs) with the flexibility to integrate additional functionalities into their products.

## **About ICE Technology**

Ventiva's patented ICE technology generates movement of air without any moving parts, noise, or vibration, leveraging the principles of electrohydrodynamic (EHD) flow to move ionized air molecules within an electric field. The ICE9 thermal management suite offers a "smart" cooling solution that continuously monitors its operation, delivering more or less airflow as an electronic system requires. Combining advanced monitoring and algorithms, the ICE9 suite's real-time software can be combined with overall system performance monitoring to provide a robust devicewide thermal solution.

## **About Ventiva**

Ventiva, a leading company in active cooling solutions for electronic devices, enables thinner, faster, and cooler high-performance devices that are lightweight, silent, and vibration-free. The company's patented ICE® technology is a pioneering all-electronic heat transfer technology created to address the thermal problems exacerbated by modern high-performance semiconductor design. Learn more at www.ventiva.com or follow us on LinkedIn.

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